Refined Hierarchical Design of Computer Chips

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August 30, 2024 -v2

1 Further Enhanced 3D Representation of Hierarchical Chip Design

Sub-module B
Sub-module C
Core Module
Base Layer

Caption: The further refined 3D diagram now includes clearer differentiation between sub-modules with enhanced shadow effects and highlighted connection arrows. These visual improvements facilitate a better understanding of the internal hierarchy and data pathways within the chip.